# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





V <sub>DSS</sub>	45V
R <sub>DS(on)</sub> (Max.)	46mΩ
I <sub>D</sub>	±4.5A
P <sub>D</sub>	2.0W

### Features

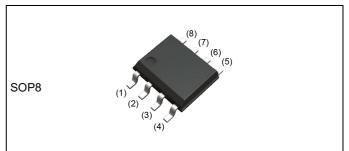
- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating ; RoHS compliant
- 4) Halogen Free

Application

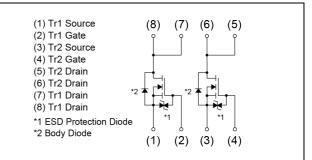
Switching

5) AEC-Q101 Qualified

#### Outline



#### Inner circuit



### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	2500
	Taping code	ТВ
	Marking	SP8K22

### • Absolute maximum ratings ( $T_a = 25^{\circ}C$ , unless otherwise specified) <Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	45	V
Continuous drain current	Ι <sub>D</sub>	±4.5	А
Pulsed drain current	۱ <sub>DP</sub> *1	±18	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Dever dissinction (total)	P <sub>D</sub> <sup>*2</sup>	2.0	14/
Power dissipation (total)	P <sub>D</sub> *3	1.4	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

#### •Thermal resistance

Deremeter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres, junction, embient (total)	$R_{thJA}^{*2}$	-	-	62.5	°C \\ \
Thermal resistance, junction - ambient (total)	$R_{thJA}^{*3}$	-	-	89.2	°C/W

# •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Devenueter	O: mah al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Onit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	45	-	-	V	
Breakdown voltage	ΔV <sub>(BR)DSS</sub>	I <sub>D</sub> = 1mA		46.8		mV/°C	
temperature coefficient	ΔTj	referenced to 25°C	-	40.0	-	mv/ C	
Zero gate voltage drain current	I <sub>DSS</sub>	$I_{DSS}$ $V_{DS} = 45V, V_{GS} = 0V$		-	1	μA	
Gate - Source leakage current	$V_{DS} = 0 V_{CS} = \pm 20 V_{CS}$		-	-	±10	μA	
Gate threshold voltage	V <sub>GS(th)</sub> V <sub>DS</sub> = 10V		1.0	-	2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = 1mA		3.9			
temperature coefficient	Δ T <sub>j</sub>	referenced to 25°C	-	-3.9	-	mV/°C	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A	-	33	46		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4.5A	-	41	57	mΩ	
		V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 4.5A	-	46	64	1	
Gate resistance	R <sub>G</sub>	$R_G$ f = 1MHz, open drain		5.0	-	Ω	
Forward Transfer		V <sub>DS</sub> = 10V, I <sub>D</sub> = 4.5A	3.5	-	-	S	

\*1 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

- \*2 Mounted on a ceramic board (30×30×0.8mm)
- \*3 Mounted on a FR4 (25×25×0.8mm)

\*4 Pulsed

# •Electrical characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cumhal	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	550	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	-	140	-	pF
Reverse transfer capacitance	ransfer capacitance C <sub>rss</sub>		-	70	-	
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} \simeq 25 V, V_{GS} = 10 V$	-	12	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 2.5A	-	18	-	
Turn - off delay time	off delay time $t_{d(off)}^{*4}$		-	42	-	ns
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	12	-	

# •Gate charge characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Symbol Conditions		Values			L locité
Parameter			Min.	Тур.	Max.	Unit
Total gate charge	Qg <sup>*4</sup>		-	6.8	9.6	
Gate - Source charge	Q <sub>gs</sub> *4	V <sub>DD</sub> ≃ 25V, I <sub>D</sub> = 4.5A V <sub>GS</sub> = 5V	-	2.0	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4		-	2.9	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

<Tr1 and Tr2>

Deremeter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	UTIIL	
Continuous forward current	۱ <sub>s</sub>	T - 25°0	-	-	1.66	^	
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25°C	-	-	18	A	
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 4.5A	-	-	1.2	V	



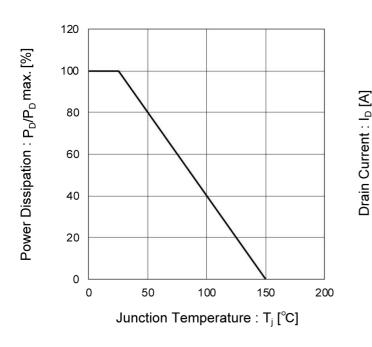


Fig.1 Power Dissipation Derating Curve

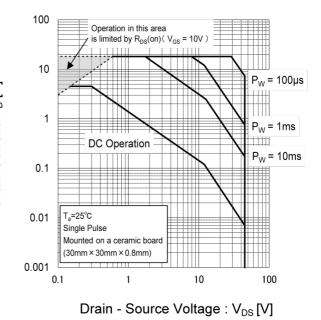
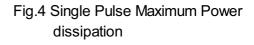
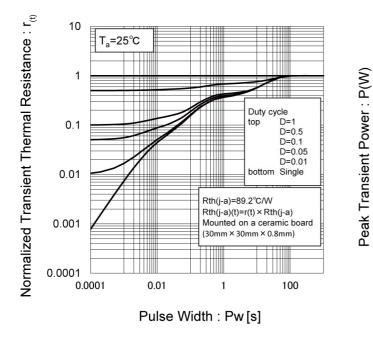


Fig.2 Maximum Safe Operating Area

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width





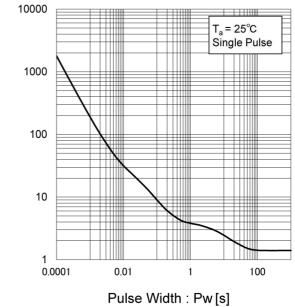
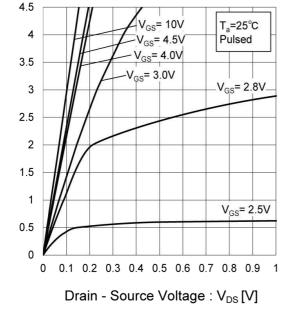
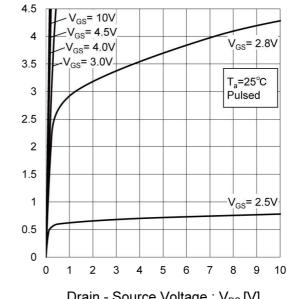




Fig.5 Typical Output Characteristics(I)

Drain Current : I<sub>D</sub> [A]





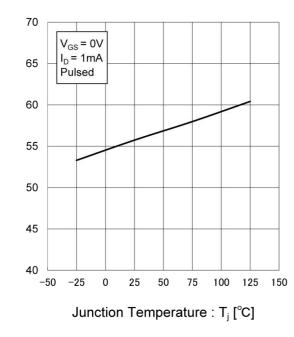
Drain Current : I<sub>D</sub> [A]

## Fig.6 Typical Output Characteristics(II)

Drain - Source Voltage :  $V_{DS}$  [V]

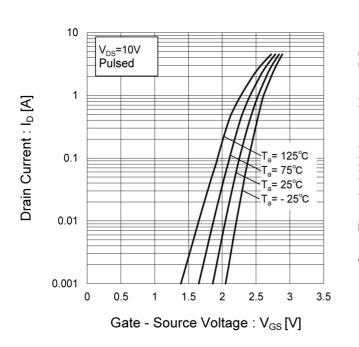
# Fig.7 Breakdown Voltage vs. Junction Temperature

Drain-Source Breakdown Voltage : V<sub>(BR)DSS</sub> [V]



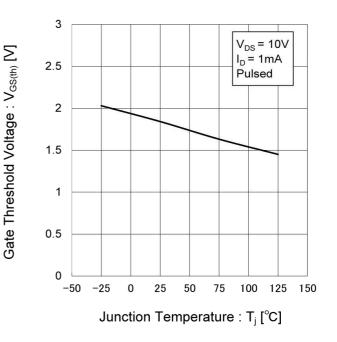


#### • Electrical characteristic curves

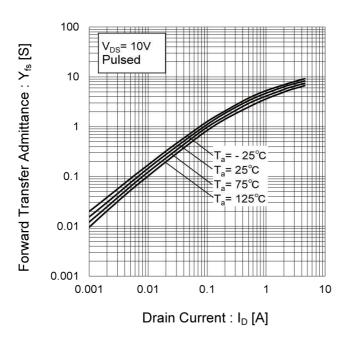


# Fig.8 Typical Transfer Characteristics

# Fig.9 Gate Threshold Voltage vs. Junction Temperature



# Fig.10 Forward Transfer Admittance vs. Drain Current





T₂=25℃

Pulsed

#### • Electrical characteristic curves

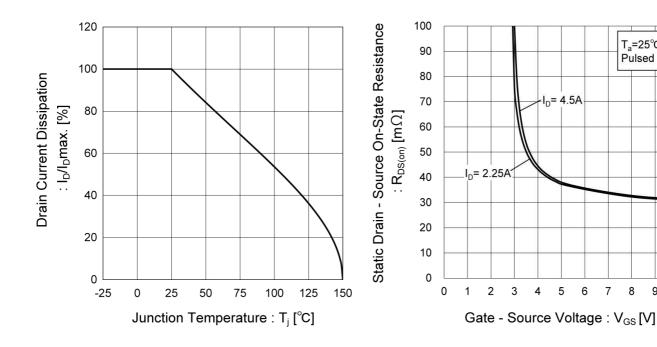
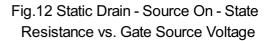


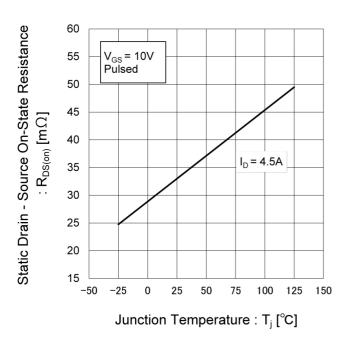
Fig.11 Drain Current Derating Curve



I<sub>D</sub>= 4.5A

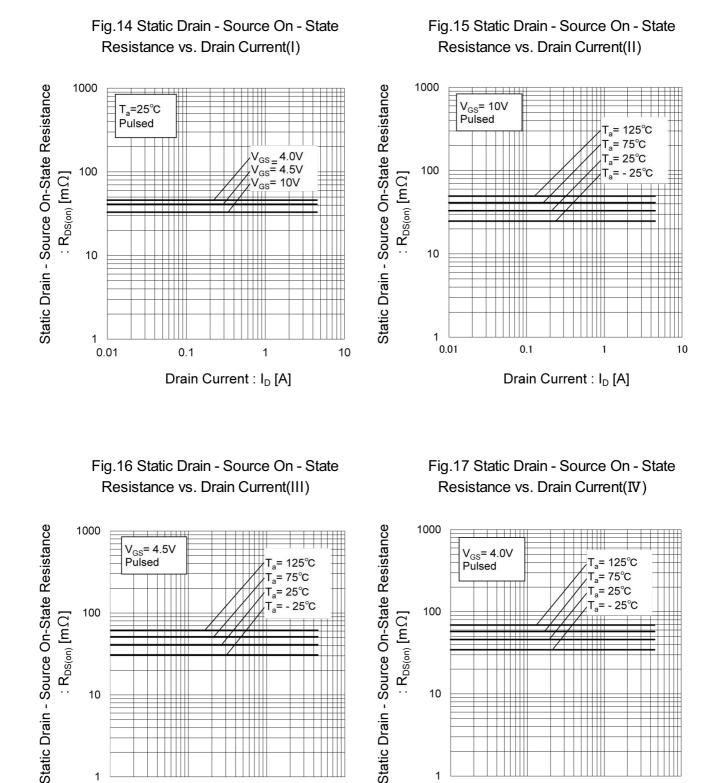
5 6 7 8 9 10

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





### • Electrical characteristic curves



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0.1

1

Drain Current : I<sub>D</sub> [A]

10

1 0.01

10

10

1

0.01



0.1

10

1

Drain Current : I<sub>D</sub> [A]

### • Electrical characteristic curves

Source Voltage

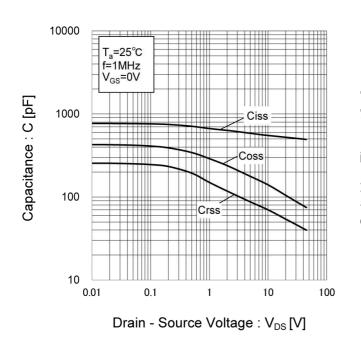
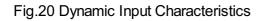


Fig.18 Typical Capacitance vs. Drain -

#### 10000 =25°C T\_ V<sub>DD</sub>=25V V<sub>GS</sub>=10V $R_{G} = 10\Omega$ 1000 Switching Time : t [ns] Pulsed 100 $t_{d(off)}$ t<sub>d(on)</sub> 10 t<sub>r</sub> E 1 0.01 0.1 1 10 Drain Current : I<sub>D</sub> [A]

# Fig.19 Switching Characteristics



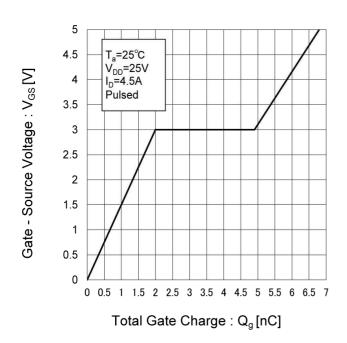
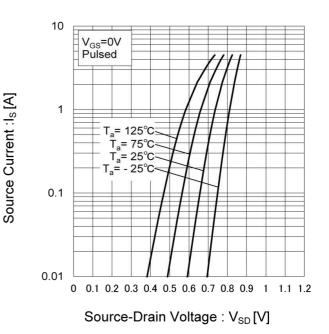


Fig.21 Source Current vs. Source Drain Voltage





# •Measurement circuits <It is the same for the Tr1 and Tr2>



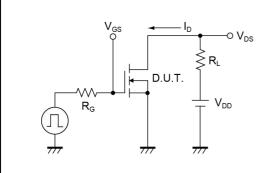


Fig.2-1 Gate Charge Measurement Circuit

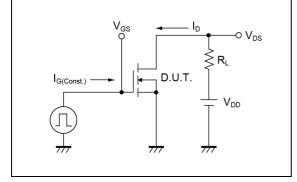
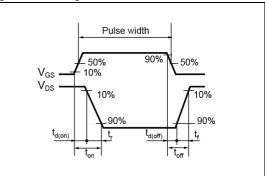
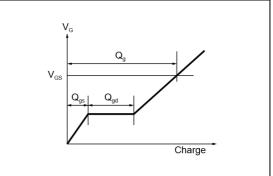


Fig.1-2 Switching Waveforms



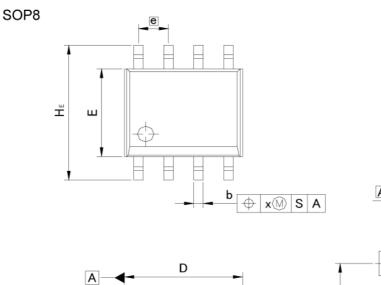


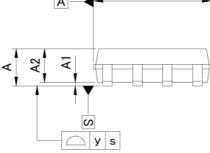


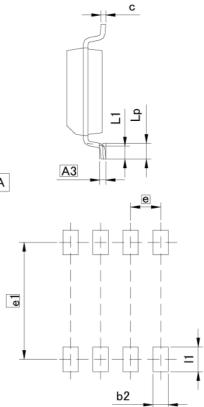


#### SP8K22FRA

#### Dimensions







Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A		1.75	-	0.069
A1	0.	15	0.0	06
A2	1.40	1.60	0.055	0.063
A3	0,	25	0.0	10
b	0.30	0.50	0.012	0.020
с	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.	27	0.0	50
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
x	0.15		0.0	06
У	0.	0.10		04

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<del></del>	0.65	<b>77</b> 4	0.026
e1	5.	15	0.1	203
11		1.15	<del></del>	0.045

Dimension in mm/inches



# Notice

#### **Precaution on using ROHM Products**

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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